The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.
The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

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Absolute Maximum Ratings at T_j=25 unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	800	V
Gate-source voltage	V_{GS}	±30	V
Continuous drain current[1], T_C=25 °C	I_D	11	A
Continuous drain current[1], T_C=100 °C		6.9	
Pulsed drain current[2], T_C=25 °C	$I_{D,\ pulse}$	33	A
Continuous diode forward current[1], T_C=25 °C	I_S	11	A
Diode pulsed current[2], T_C=25 °C	$I_{S,\ pulse}$	6.9	A
Power dissipation[3], T_C=25 °C	P_D	34	W
Single pulsed avalanche energy[5]	E_{AS}	400	mJ
MOSFET dv/dt ruggedness, V_{DS} 640 V	dv/dt	50	V/ns
Reverse diode dv/dt, V_{DS} 640 V, I_{SD} D	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	3.68	°C/W
Thermal resistance, junction-ambient[4]	R	62.5	°C/W

Electrical Characteristics at T_j=25 unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	800			V	V_{GS}=0 V, I_D=250 A
		850				V_{GS}=0 V, I_D , T_j=150 °C
Gate threshold voltage	$V_{GS(th)}$	2.9		3.9	V	V_{DS}=V_{GS}, I_D=250 A
Drain-source on-state resistance	$R_{DS(ON)}$		0.30	0.38		V_{GS}=10 V, I_D=5.5 A
			0.69			V_{GS}=10 V, I_D=5.5 A, T_j=150 °C
Gate-source leakage current	I_{GSS}			100	nA	V_{GS}=30 V
				-100		V_{GS}=-30 V
Drain-source leakage current	I_{DSS}			10	A	V_{DS}=800 V, V_{GS}=0 V

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		1442.9		pF	V_{GS}=0 V, V_{DS}=50 V, 00 kHz
Output capacitance	C_{oss}		83.7		pF	
Reverse transfer capacitance	C_{rss}		1.9		pF	
Turn-on delay time	$t_{d(on)}$		28.4		ns	V_{GS}=10 V, V_{DS}=400 V, R_G=10 I_D=6 A
Rise time	t_r		15.8		ns	
Turn-off delay time	$t_{d(off)}$		50.2		ns	
Fall time	t_f		4.7		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		22.2		nC	V_{GS}=10 V, V_{DS}=400 V, I_D=6 A
Gate-source charge	Q_{gs}		6.8		nC	
Gate-drain charge	Q_{gd}		6.3		nC	
Gate plateau voltage	$V_{plateau}$		5.7		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V_{SD}			1.3	V	I_S=11 A, V_{GS}=0 V
Reverse recovery time	t_{rr}		262.0		ns	V_R=400 V, I_S=6 A,
Reverse recovery charge	Q_{rr}		3.9		C	
Peak reverse recovery current	I_{rrm}		29.1		A	

Note

1) Calculated continuous current based on maximum allowable junction temperature.
2) Repetitive rating; pulse width limited by max. junction temperature.
3) Pd is based on max. junction temperature, using junction-case thermal resistance.
4) The value of R is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
5) V_{DD}=100 V, V_{GS}=10 V, L=10 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

Figure 1. Typ. output characteristics	**Figure 2. Typ. transfer characteristics**
Figure 3. Typ. capacitances	**Figure 4. Typ. gate charge**

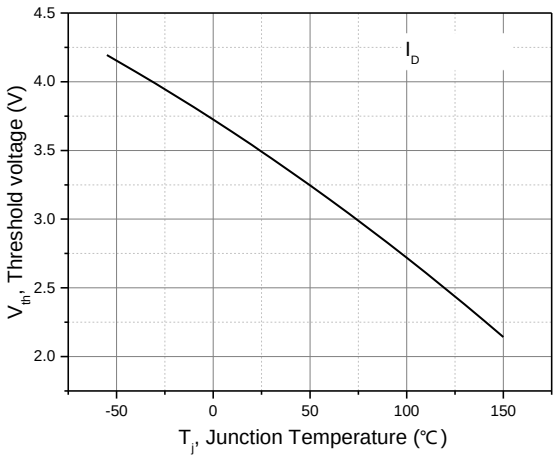


Figure 7. Threshold voltage

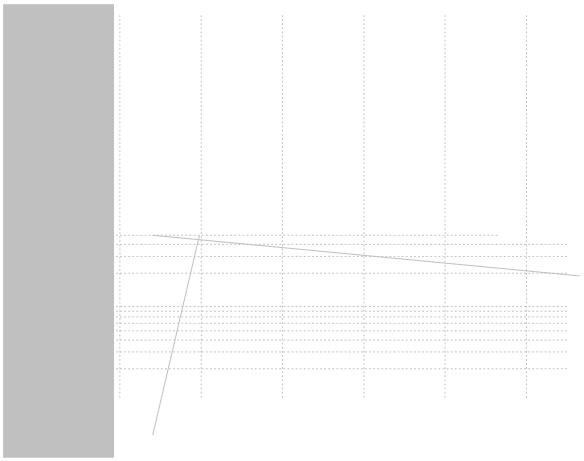


Figure 8. Forward characteristic of body diode

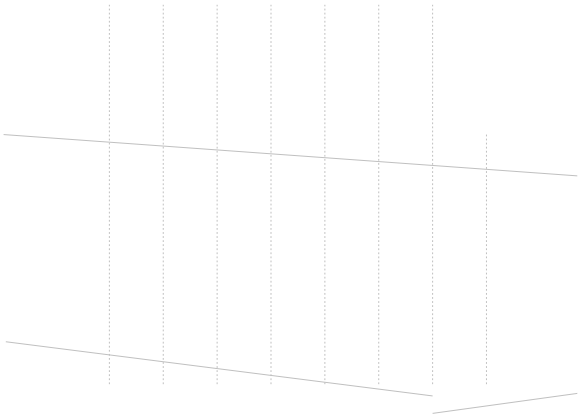


Figure 9. Drain-source on-state resistance

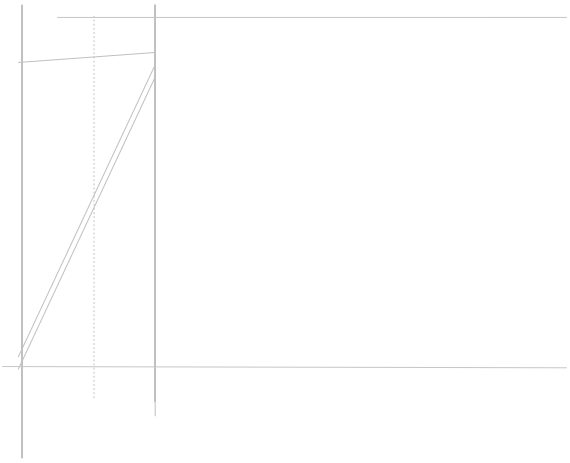


Figure 10. Drain current

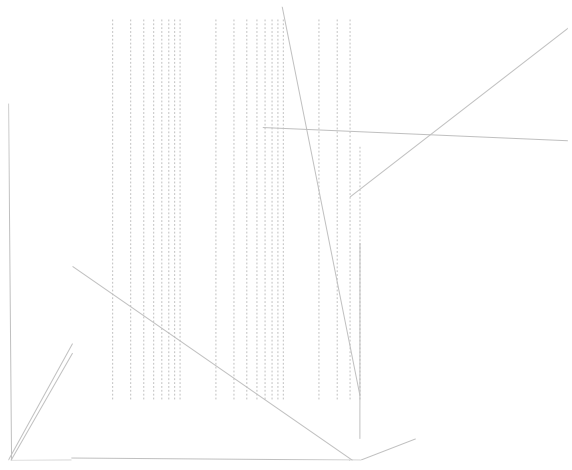


Figure 11. Safe operation area T_C=25 °C

Test circuits and waveforms

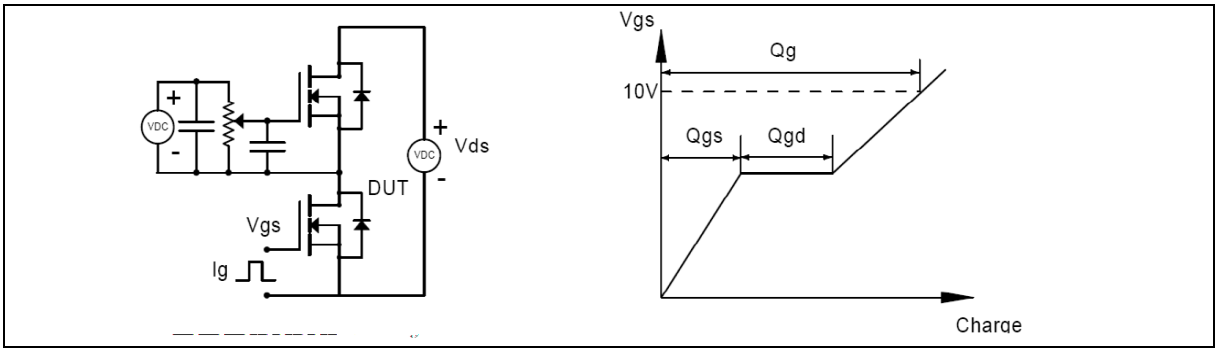


Figure 1. Gate charge test circuit & waveform

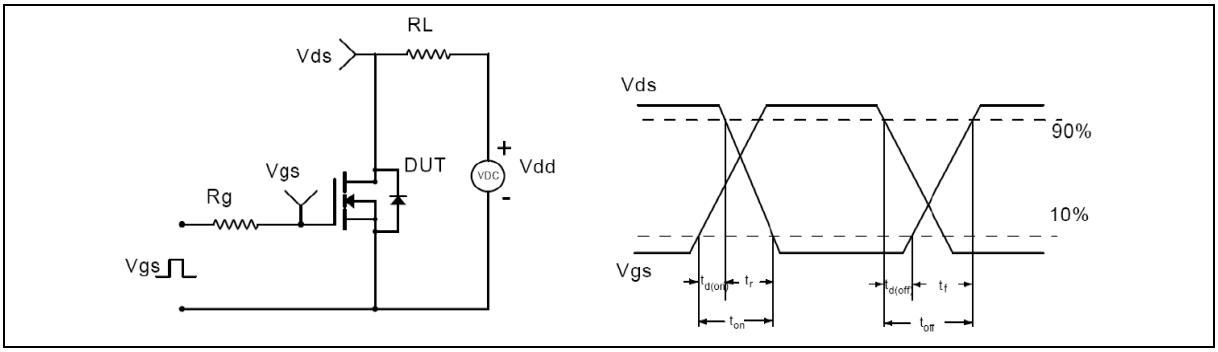


Figure 2. Switching time test circuit & waveforms

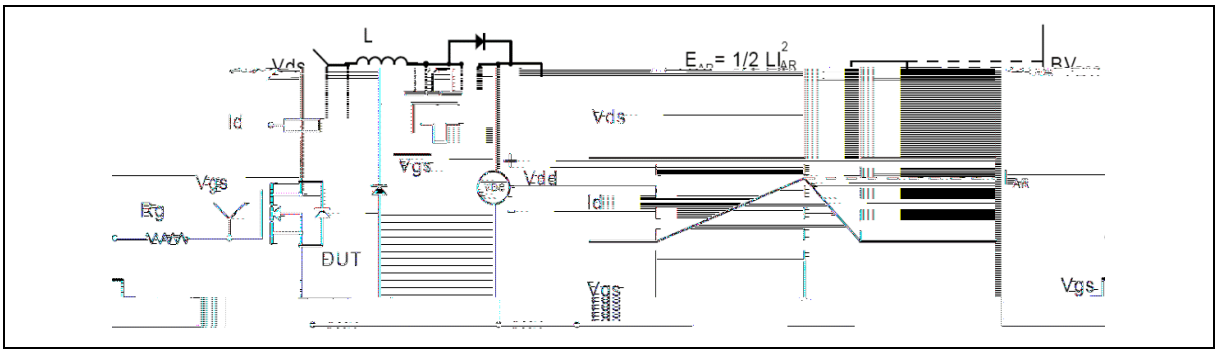


Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

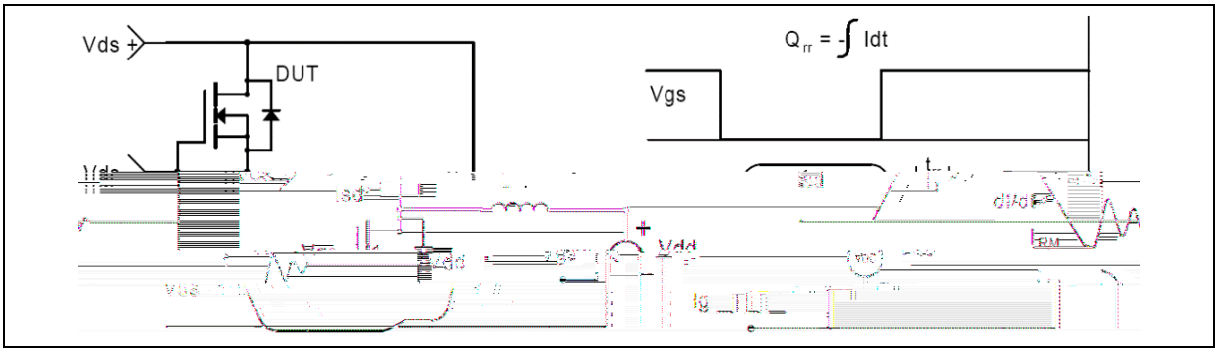
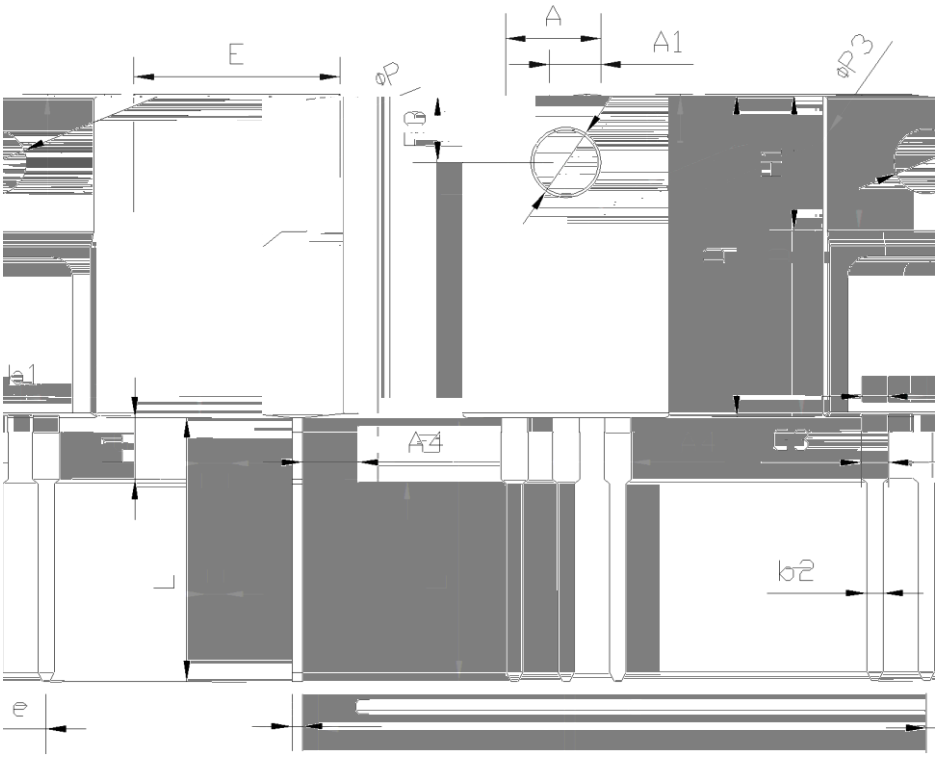


Figure 4. Diode reverse recovery test circuit & waveforms

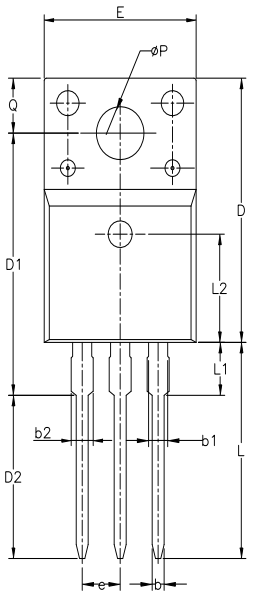
Package Information

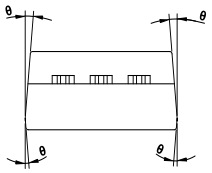


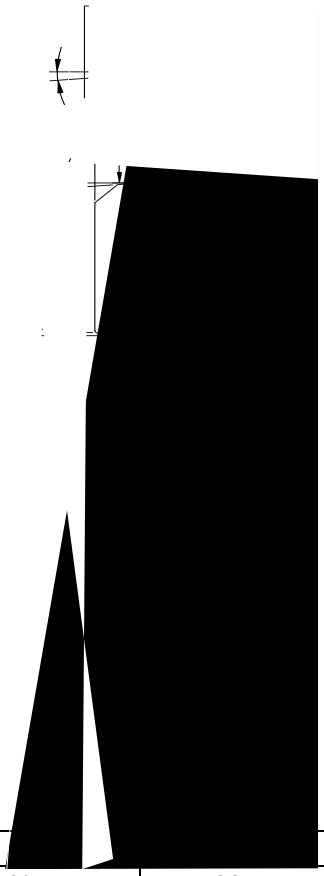
Symbol	mm		
	Min	Nom	Max
E	9.96	10.16	10.36
A	4.50	4.70	4.90
A1	2.34	2.54	2.74
A4	2.56	2.76	2.96
c	0.40	0.50	0.65
D	15.57	15.87	16.17
H1	6.70REF		
e	2.54BSC		
L	12.68	12.98	13.28
L1	2.88	3.03	3.18
	3.03	3.18	3.38
	3.15	3.45	3.65
F3	3.15	3.30	3.45
G3	1.25	1.35	1.55
b1	1.18	1.28	1.43
b2	0.70	0.80	0.95

Version 1: TO220F-C package outline dimension

Package Information







Symbol			
	Min	Nom	Max
A	4.40	4.50	4.60
A1	1.27	1.30	1.33
A2	2.30	2.40	2.50
b	0.70	-	0.90
b1	1.27	-	1.40
c	0.45	0.50	0.60
D	15.30	15.70	16.10
D1	9.10	9.20	9.30
D2	13.10	-	13.70
E	9.70	9.90	10.20
E1	7.80	8.00	8.20
e	2.54BSC		
e1	5.08BSC		
H1	6.30	6.50	6.70
L	12.78	13.08	13.38
L1	-	-	3.50
L2	4.60REF		
	3.55	3.60	3.65
Q	2.73	-	2.87
1	1		

Version 2: TO220F-J package outline dimension

Ordering Information

Package Type	Units/ Tube	Tubes/ Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO220F-C	50	20	1000	6	6000
TO220F-J	50	20	1000	5	5000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG80R380FF	TO220F	yes	yes	yes

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